## **LNA2801L**

### GaAlAs on GaAs Infrared Light Emitting Diode

For optical control systems

#### ■ Features

- High-power output, high-efficiency: I<sub>e</sub> = 6 mW/sr (min.)
- Emitted light spectrum suited for silicon photodetectors
- Good radiant power output linearity with respect to input current
- \$\phi 3\$ plastic package

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	75	mW	
Forward current	$I_{\mathrm{F}}$	50	mA	
Pulse forward current *	$I_{FP}$	1	A	
Reverse voltage	$V_R$	3	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: f = 100 Hz, Duty cycle = 0.1%

#### ■ Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

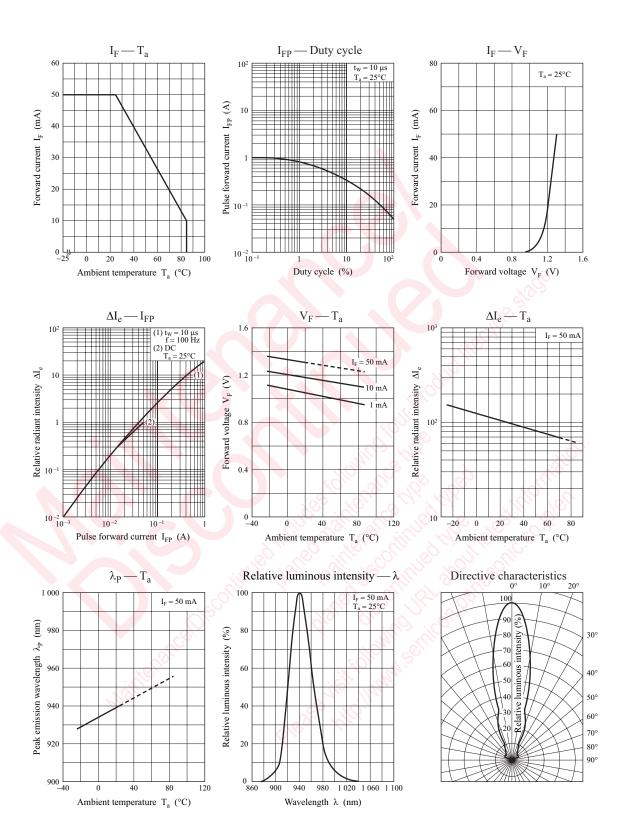
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Center radiant intensity	I <sub>e</sub>	$I_F = 20 \text{ mA}$	6.0	Chilling !	0/8,	mW/sr
Reverse current	$I_R$	$V_R = 3 V$	5 196	6	10	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 50 \text{ mA}$	OIL.	1.3	1.5	V
Terminal capacitance	Ct	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$	5 185	35		pF
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 50 \text{ mA}$	60,	940		nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Half-power angle	θ	The angle when the center radiant intensity is halved.		15		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 1 MHz

$$f_C: 10 \times log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$

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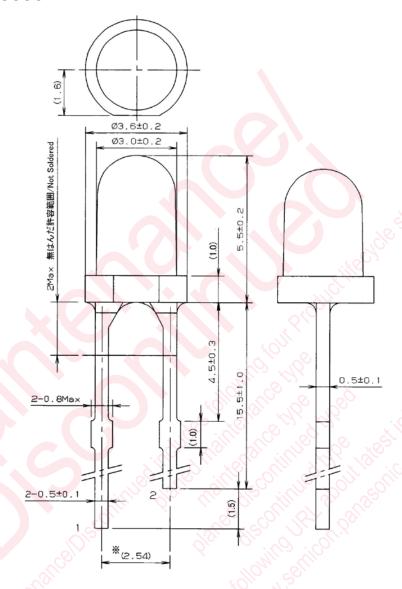


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■ Package (Unit: mm)

## LEXLTN2S0006



- Pin name
  - 1: Anode
  - 2: Cathode

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